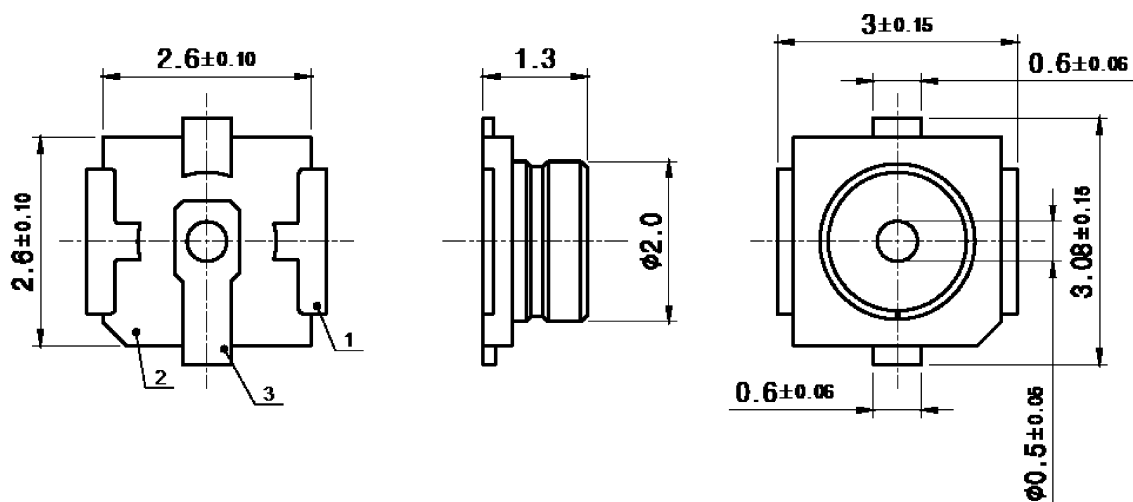


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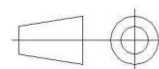
SERIES **MML**

PART NUMBER **R302302000**



1. MML-Body
2. MML-Insulator
3. MML-Signal Pin

All dimensions are in mm.



COMPONENTS	MATERIALS	PLATING (μm)
Body	BRONZE	GOLD
Center contact	BRASS	GOLD
Outer contact		
Insulator	LCP	
Gasket		
Others parts		
-	-	-
-	-	-

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SERIES **MML**

PART NUMBER **R302302000**

PACKAGING

Standard	Unit	Other
5000	Contact us	Contact us

ELECTRICAL CHARACTERISTICS

Impedance	50	Ω
Frequency	0-6	GHz
VSWR	1.35 +	0 x F(GHz) Maxi
Insertion loss	NA	\sqrt{F} (GHz) dB Maxi
RF leakage	NA	- F(GHz)) dB Maxi
Voltage rating	60	Veff Maxi
Dielectric withstanding voltage	200	Veff mini
Insulation resistance	500	M Ω mini

ENVIRONMENTAL

Operating temperature	-40/+90	°C
Hermetic seal	NA	Atm.cm3/s
Panel leakage	NA	

MECHANICAL CHARACTERISTICS

Center contact retention	NA	N mini
Axial force – Mating End	NA	N mini
Axial force – Opposite end	NA	N mini
Torque	NA	N.cm mini
Recommended torque		
Mating	NA	N.cm
Panel nut	NA	N.cm
Mating life	30	Cycles mini
Weight	0.02	g

SPECIFICATION

OTHER CHARACTERISTICS

Assembly instruction:

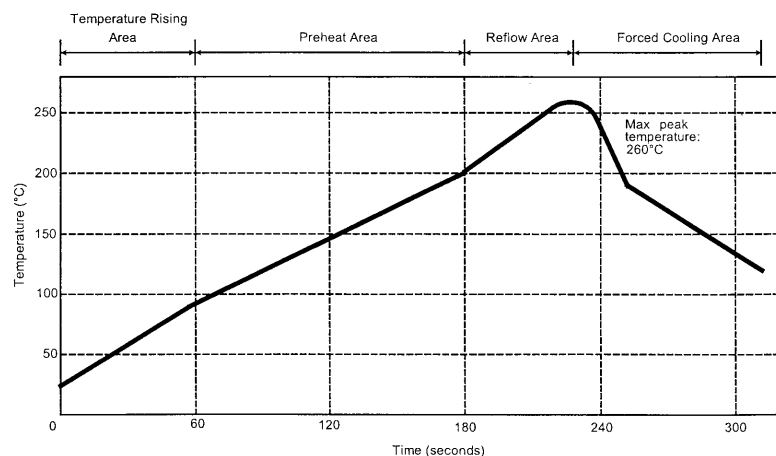
Others:

SOLDER PROCEDURE

1. Deposit solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
We advise a thickness of 150 microm (5.850 microinch). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component .
Adhesive agents must not be used on the receptacle.
3. This process of soldering has been tested with convection oven .Below please find ,the typical profile to use.
4. The cleaning of printed circuit boards is not obliged .
5. Verification of solder joints and position of the component by visual inspection.

NOTE : The receptacle and the plug must not be mated before completion of this procedure

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

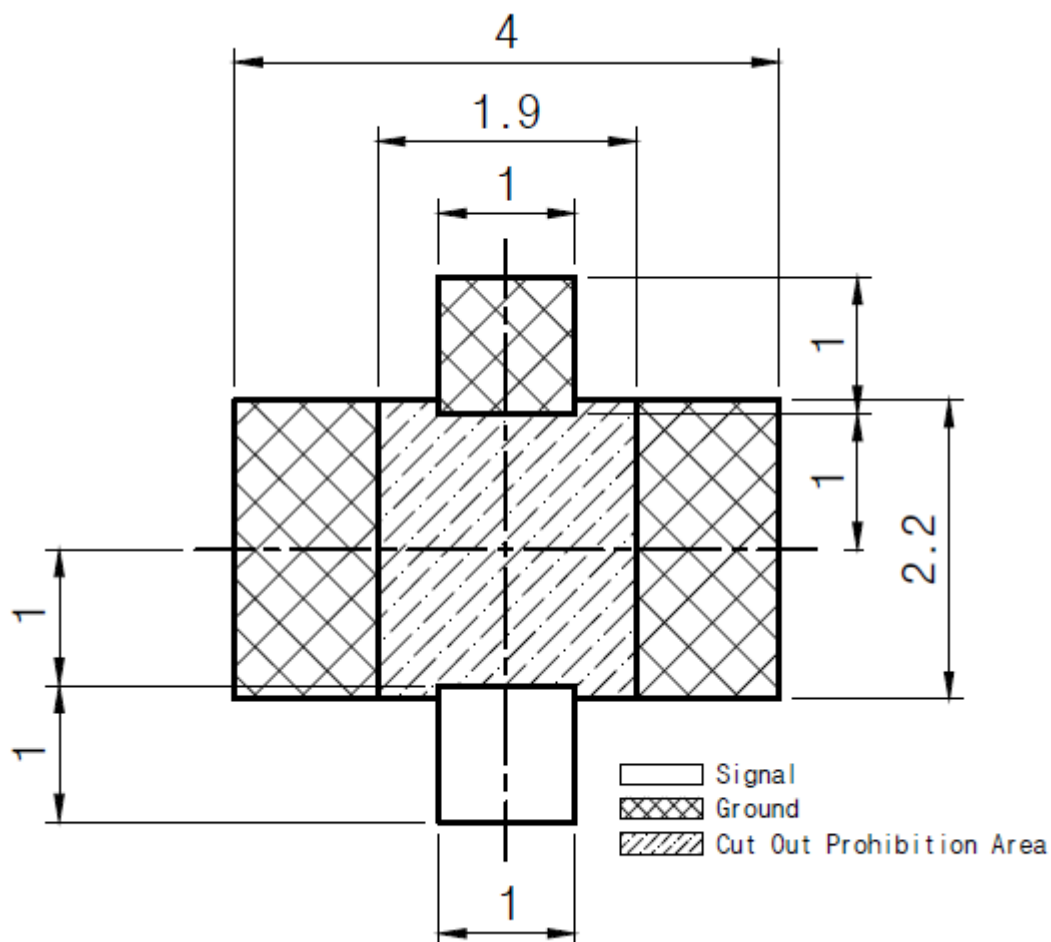
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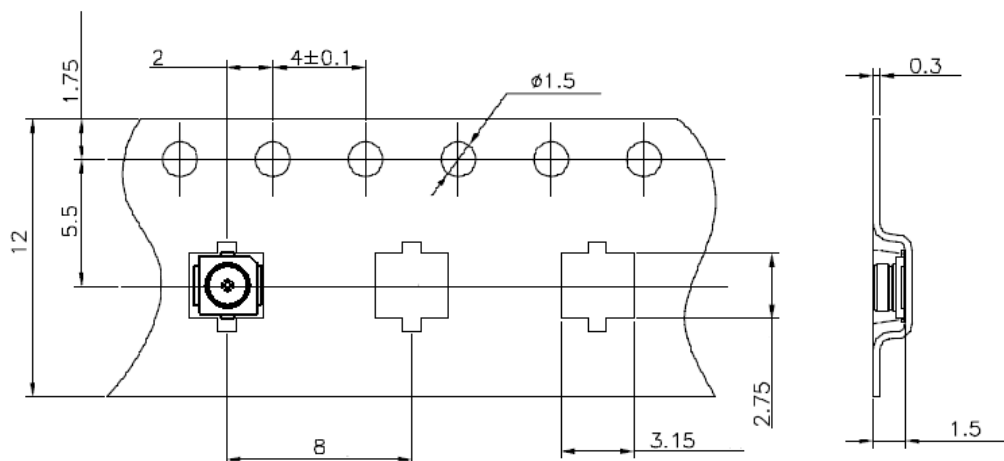
RECOMMENDED PCB DIMENSIONS



Tolerance: $\pm 0.05\text{mm}$

PACKING

Embossed Taping



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Reel

